



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Albert W. Chan, et al.

Serial No.: 09/757,364

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For: **METHOD FOR JOINING
LARGE SUBSTRATES**

Group Art Unit: 1733

Examiner: John T. Haran

Attorney Docket: 6136/53650(25916-188)

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(37 C.F.R. § 1.8A)
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January 31, 2003

Mary M. Padilla
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100/TK
2/2/03

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

The following Amendment and Remarks are made in response to the Office Action
mailed November 1, 2002. Reexamination and reconsideration of the application in light of the
following Amendment and Remarks are respectfully requested.

In the Claims:

Please amend claims 10, 14 and 15 as follows (please substitute the following amended
claim for the pending claims with the same numbers):

R1 *SUB B37* 10 (Once Amended) The method of Claim 7 wherein said polymer fluxing agent
comprises a beta phenylacid and/or a beta phenylhydroxyacid.

R2 *SUB B37* 14. (Once Amended) The method of Claim 5, wherein said solder bumps comprise a
solder material fluxing agent, wherein said liquid polymeric material comprises a polymer
fluxing agent, wherein said polymer fluxing agent comprises a beta phenylacid and/or a beta